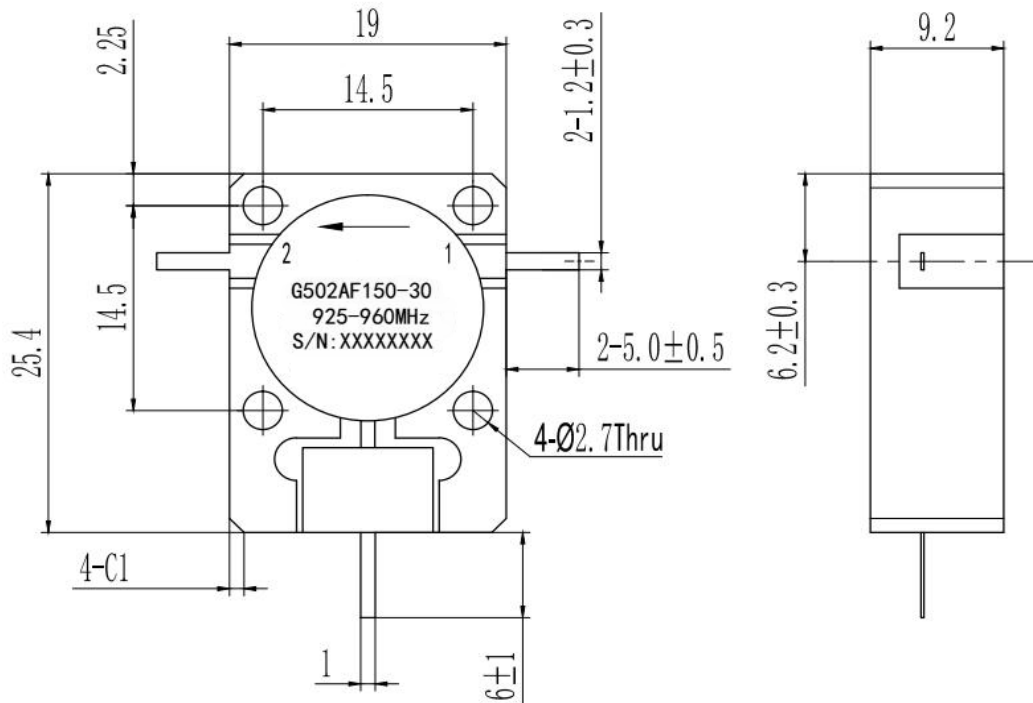


### 1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

### 2.Dimension



### 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G502A[925-960]MHz	0.925	0.960	0.943	0.035	22	0.3	1.17	150	
G502A[1600-1630]MHz	1.600	1.630	1.6150	0.030	23	0.25	1.15	150	
G502A[1689-1710]MHz	1.689	1.710	1.6995	0.021	23	0.2	1.15	150	
G502A[1800-2200]MHz	1.800	2.200	2.0000	0.400	22	0.3	1.2	100	
G502A[1805-1880]MHz	1.805	1.880	1.8375	0.075	23	0.25	1.17	150	
G502A[2000-2500]MHz	2.000	2.500	2.2500	0.500	18	0.4	1.3	150	
G502A[2100-2200]MHz	2.100	2.200	2.1500	0.100	22	0.3	1.2	150	
G502A[2300-2400]MHz	2.300	2.400	2.3500	0.100	22	0.25	1.17	150	-65
G502A[2555-2660]MHz	2.555	2.660	2.6075	0.105	22	0.25	1.17	150	-65
G502A[3100-3500]MHz	3.100	3.500	3.3000	0.400	20	0.35	1.2	100	
G502A[3400-4200]MHz	3.400	4.200	3.800	0.800	15	0.45	1.4	150	